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**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claims 1-5 (canceled).

Claim 6 (currently amended): A method of manufacturing a surface acoustic wave device, said method comprising the steps of:

providing a piezoelectric body;

disposing a metal film on the piezoelectric body, said metal film having a higher density than said piezoelectric body;

forming a plurality of interdigital transducers defined by portions of the metal film disposed on the piezoelectric body;

cutting said piezoelectric body into a plurality of surface acoustic wave elements, each of said surface acoustic elements having at least one interdigital transducer;

simultaneously etching said at least one interdigital transducer and said piezoelectric body; and

packaging at least one of the surface acoustic wave elements.

Claim 7 (currently amended): The method of claim 6, wherein said step of etching includes adjusting ~~the~~ a thickness of said interdigital transducer and said piezoelectric body.

Claim 8 (original): The method of claim 6, wherein said step of etching includes ion bombarding said at least one of the interdigital transducers and said piezoelectric

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body.

Claim 9 (original): The method of claim 6, further comprising the step of ion bombarding said at least one of the interdigital transducers and said cut piezoelectric body after said step of packaging.

Claim 10 (currently amended): The method of claim 6, further comprising the step of adjusting the a thickness of said metal film.

Claim 11 (original): The method of claim 10, wherein said step of adjusting the thickness is performed by etching said metal film using a wet etchant.

Claim 12 (original): The method of claim 6, wherein said step of etching includes ion bombarding said at least one of the interdigital transducers and said piezoelectric body by applying at least one of Ar gas, carbon fluoride gas, a chlorine gas, and an N<sub>2</sub> gas to said interdigital transducers and said piezoelectric body.

Claims 13-20 (canceled).